

ABSTRACT OF THE DISCLOSURE

Apparatus and method for removing copper from wafer edge. The apparatus of the invention includes a bath tank for containing a chemical bath, a rotatable wafer chuck for holding a wafer vertical to the chemical bath, wherein at least the edge of the wafer is covered with a metal layer, and a sliding element is disposed on one end of the rotatable wafer chuck such that the rotatable wafer chuck can move in a vertical direction to the chemical bath.